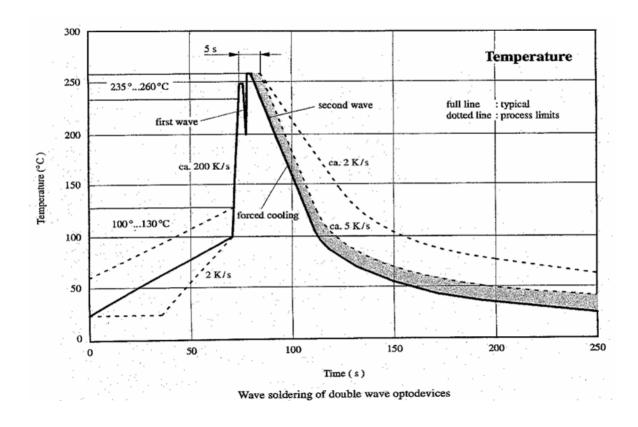


## LAMP APPLICATION (PB FREE SOLDERJING)

## Apply to LAMP (DIP) SERIES.

## **Description:**

- (1) Manual soldering (Solder Iron)
  - (1.1) Temperature at tip of the iron:350 $^{\circ}$ C Max.
  - (1.2) It's banned to load any stress on the resin during soldering.
  - (1.3) Soldering time: 3sec.Max.(one time only.)
  - (1.4) Leave 3mm of minimum distance from the base of the epoxy.
- (2) Dip Soldering (Wave Soldering-Solder Bath)
  - (2.1) Leave 3mm of minimum distance from the base of the epoxy. Soldering beyond the base of the tie bar (stand off) is recommended.
  - (2.2) When soldering, do not put stress on the LEDs during heating.
  - (2.3) Cutting the lead frames at high temperatures may cause LED failure.
  - (2.4) Never take next process until the component is cooled down to room temperature after reflow.
  - (2.5) After soldering, do not warp the circuit board.
  - (2.6) The recommended dip soldering profile is the following.



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